

AMENDMENTS TO THE CLAIMS

Please amend claims 1-10 as follows:

1. (Currently Amended) A semiconductor ~~apparatus~~ device comprising:

a semiconductor element ~~device to be mounted on a circuit board, said device~~
having a ~~device~~ main surface, peripheral ~~device~~ edges bounding the main surface
and a ~~peripheral~~ side surface extending from said peripheral ~~device~~ edges and
~~bounding said device~~ edges, said semiconductor element having a plurality of
electrodes formed thereon;

a plurality of conductive posts each of which is electrically connected to a
corresponding one of the plurality of electrodes formed on the semiconductor device
element, said conductive posts having outer edges;

a resin covering over said ~~device~~ main surface of the semiconductor element
for sealing said ~~device~~ main surface of the semiconductor element, said resin
~~covering leaving exposed said device peripheral side surface~~ of the semiconductor
element exposed; and

~~means for mounting the device onto a circuit board by soldering, including a~~
plurality of conductive bumps respectively positioned on an outer end of each of the
conductive posts ~~for soldering onto the circuit board~~, wherein the outer edges of said
conductive posts are separated from said ~~device~~ peripheral edges by a distance
narrower than the height of the conductive posts.

2. (Currently Amended) A semiconductor ~~apparatus~~ device according to
claim 1, wherein the distance is in a range between 50 and 100 micrometers.

3. (Currently Amended) A semiconductor ~~apparatus~~ device according to claim 1, wherein the electrodes are ~~semiconductor device is provided with a plurality of electrode pads connected to the conductive posts, the electrode pads being arranged on a line extending in a center portion of the semiconductor device~~ element.

4. (Currently Amended) A semiconductor ~~apparatus~~ device according to claim 1, wherein ~~the semiconductor device is provided with a plurality of electrode pads connected to the conductive posts, each of the~~ electrodes is ~~electrode pads being arranged between two adjacent conductive posts.~~

5. (Currently Amended) A semiconductor ~~apparatus~~ device according to claim 1, wherein ~~the semiconductor device is provided with a plurality of electrode pads connected to the conductive posts, each of the~~ electrodes is ~~electrode pads being arranged directly under a corresponding conductive post.~~

6. (Currently Amended) A semiconductor ~~apparatus~~ device according to claim 1, wherein the conductive bumps are of solder.

7. (Currently Amended) A semiconductor ~~apparatus~~ device comprising:
a semiconductor element ~~device~~ having a ~~device~~ main surface, peripheral ~~device~~ edges bounding the main surface and a ~~peripheral~~ side surface extending

from said peripheral device edges and bounding said device edges, said semiconductor element having a plurality of electrodes formed thereon;

a plurality of conductive posts each of which is electrically connected to a corresponding one of the plurality of electrodes formed on the semiconductor device element, said posts having ~~post~~ outer ends and ~~post~~ peripheral surfaces extending from said device main surface of the semiconductor element to said ~~post~~ outer ends of the conductive posts, said ~~post~~ peripheral surfaces having ~~post~~ inner end portions extending from said device main surface of the semiconductor element, and ~~post~~ outer end portions extending from said ~~post~~ inner end portions to said ~~post~~ outer ends of the conductive posts;

~~means for mounting the device onto a circuit board by soldering, including a plurality of conductive bumps respectively positioned on said ~~post~~ outer ends~~ of the conductive posts for soldering onto the circuit board; and

a molding resin covering said device main surface of the semiconductor element, wherein said molding resin includes a step portion along the entirety of a peripheral portion of said device main surface of the semiconductor element, wherein the step covering portion is formed such that said ~~post~~ inner end portions of the conductive posts are covered by said molding resin, and while leaving exposed said ~~post~~ outer end portions of the conductive posts and said device peripheral side surface of the semiconductor device are exposed.

8. (Currently Amended) A semiconductor ~~apparatus~~ device according to claim 7, wherein the difference in level between the upper portion and lower portion of the step portion is half of a thickness of the mold resin.

9. (Currently Amended) A semiconductor ~~apparatus~~ device according to claim 7, wherein the difference in level between the upper portion and lower portion of the step portion is in a range between 40 and 60 micrometers.

10. (Currently Amended) A semiconductor ~~apparatus~~ device according to claim 7, wherein the conductive bumps are of solder.

11-23. (Canceled)